

**DMN3730UFB4**

**30V N-CHANNEL ENHANCEMENT MODE MOSFET**

**Product Summary**

$V_{(BR)DSS}$	$R_{DS(on)}$	$I_D$ $T_A = +25^\circ C$
30V	460m $\Omega$ @ $V_{GS} = 4.5V$	0.9A
	560m $\Omega$ @ $V_{GS} = 2.5V$	0.7A

**Description**

This MOSFET is designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

**Applications**

- Load Switch
- Portable Applications
- Power Management Functions

**Features and Benefits**

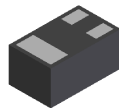
- 0.4mm Ultra Low Profile Package for Thin Application
- 0.6mm<sup>2</sup> Package Footprint, 10 times Smaller than SOT23
- Low  $V_{GS(th)}$ , can be driven directly from a battery
- Low  $R_{DS(on)}$
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **ESD Protected Gate 2kV**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

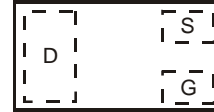
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.001 grams (Approximate)



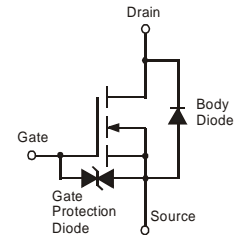
X2-DFN1006-3



Bottom View



Top View





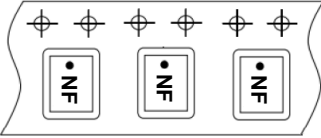
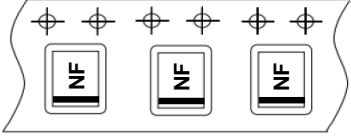

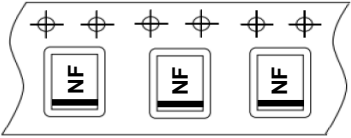
Equivalent Circuit

**Ordering Information (Note 4)**

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN3730UFB4-7	NF	7	8	3,000
DMN3730UFB4-7B	NF	7	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**

<p><b>DMN3730UFB4-7</b></p>	<div style="display: flex; justify-content: space-around;"> <div style="text-align: center;">  <p>Top View Dot Denotes Drain Side</p> </div> <div style="text-align: center;"> <p>From date code 1527 (YYWW), this changes to:</p>  <p>Top View Bar Denotes Gate and Source Side</p> </div> </div> <div style="display: flex; justify-content: space-around; margin-top: 20px;">   </div>
<p><b>DMN3730UFB4-7B</b></p>	<div style="text-align: center;">  <p>Top View Bar Denotes Gate and Source Side</p> </div> <p style="text-align: center; margin-top: 20px;">NF = Part Marking Code</p> <div style="text-align: center; margin-top: 20px;">  </div>

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	30	V
Gate-Source Voltage		V <sub>GSS</sub>	±8	
Continuous Drain Current	V <sub>GS</sub> = 4.5V	I <sub>D</sub>	(Note 6)	0.91
			T <sub>A</sub> = +70°C (Note 6)	0.73
			(Note 5)	0.75
Pulsed Drain Current		I <sub>DM</sub>	3	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 6)	P <sub>D</sub>	0.69	W
	(Note 5)		0.47	
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>θJA</sub>	180	°C/W
	(Note 5)		258	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Notes:
5. For a device surface mounted on a minimum recommended pad layout of an FR4 PCB, in still air conditions; the device is measured when operating in steady-state condition.
  6. Same as note 4, except the device measured at t ≤ 10 seconds.
  7. Same as note 4, except the device is pulsed at duty cycle of 1% for a pulse width of 10μs.

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 10μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	1	μA	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	3	μA	V <sub>GS</sub> = ±8V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.45	—	0.95	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
Static Drain-Source On-Resistance (Note 8)	R <sub>DS(on)</sub>	—	—	460	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 200mA
		—	—	560		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 100mA
		—	—	730		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 75mA
Forward Transfer Admittance	Y <sub>fs</sub>	40	—	—	mS	V <sub>DS</sub> = 3V, I <sub>D</sub> = 10mA
Diode Forward Voltage (Note 8)	V <sub>SD</sub>	—	0.7	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 300mA
<b>DYNAMIC CHARACTERISTICS (Note 9)</b>						
Input Capacitance	C <sub>iSS</sub>	—	64.3	—	pF	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oSS</sub>	—	6.1	—	pF	
Reverse Transfer Capacitance	C <sub>rSS</sub>	—	4.5	—	pF	
Gate Resistance	R <sub>g</sub>	—	70	—	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge	Q <sub>g</sub>	—	1.6	—	nC	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 1A
Gate-Source Charge	Q <sub>gs</sub>	—	0.2	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	0.2	—	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	—	3.5	—	ns	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1A V <sub>GS</sub> = 10V, R <sub>G</sub> = 6Ω
Turn-On Rise Time	t <sub>r</sub>	—	2.8	—	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	—	38	—	ns	
Turn-Off Fall Time	t <sub>f</sub>	—	13	—	ns	

Notes: 8. Measured under pulsed conditions to minimize self-heating effect. Pulse width ≤ 300μs; duty cycle ≤ 2%  
9. For design aid only, not subject to production testing.

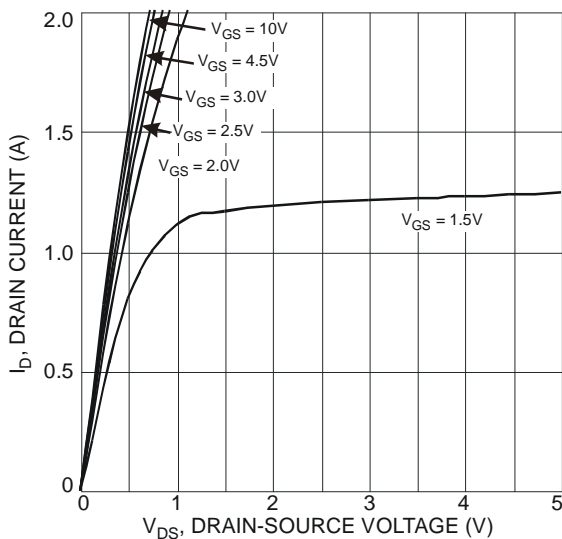


Fig. 1 Typical Output Characteristic

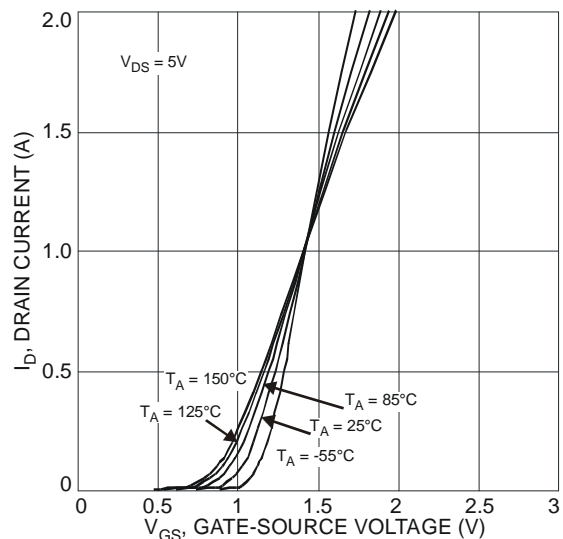


Fig. 2 Typical Transfer Characteristic

**DMN3730UFB4**

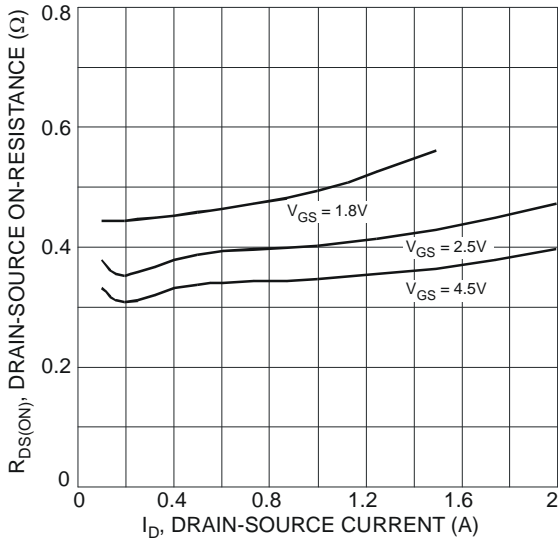


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

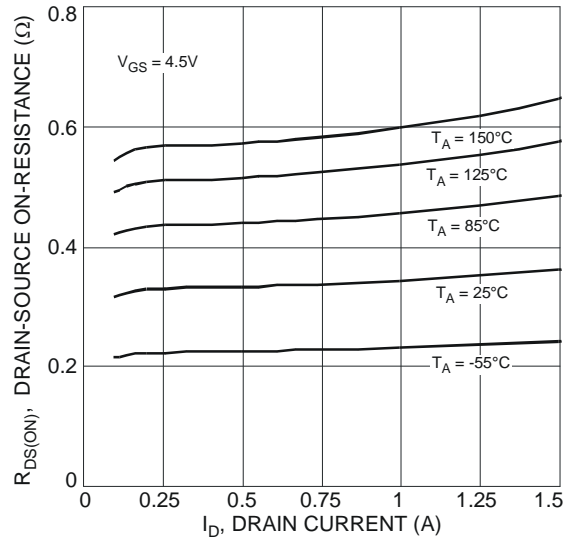


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

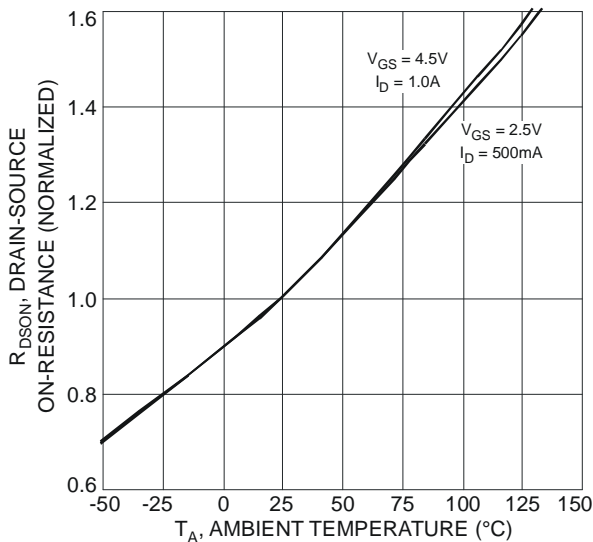


Fig. 5 On-Resistance Variation with Temperature

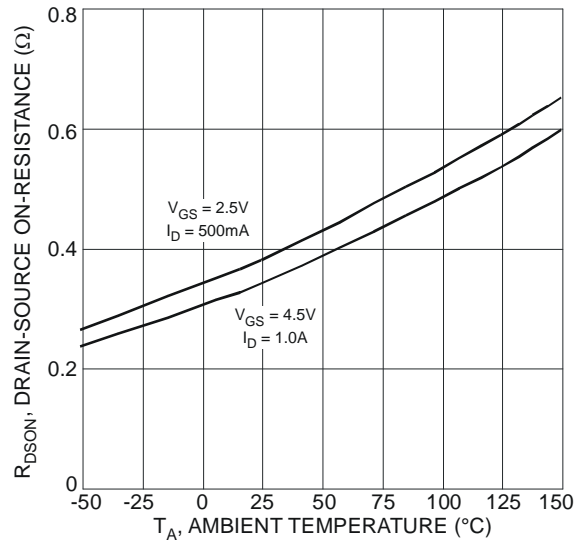


Fig. 6 On-Resistance Variation with Temperature

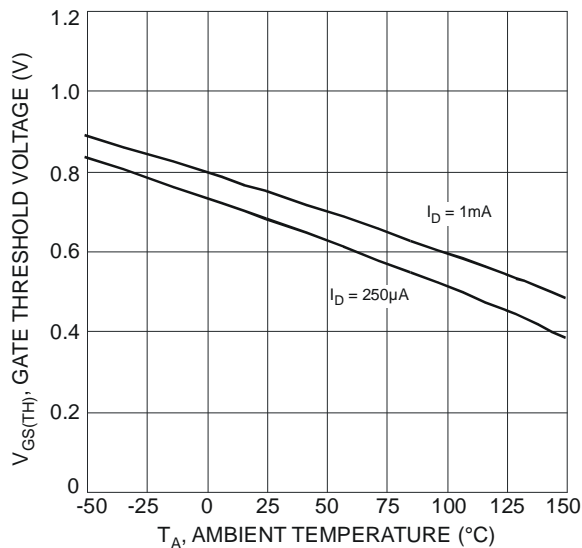


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

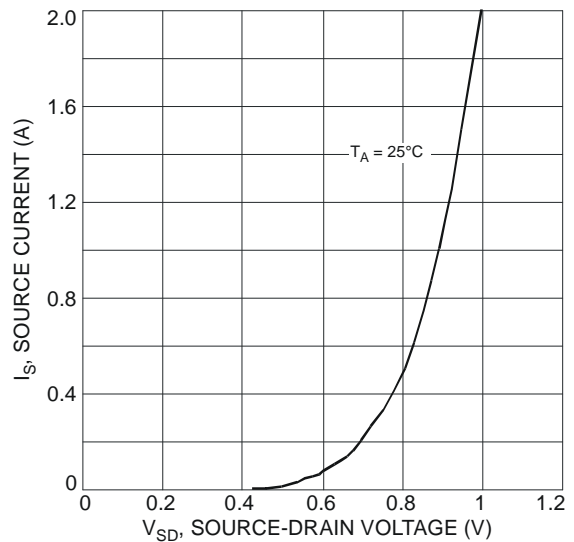


Fig. 8 Diode Forward Voltage vs. Current

**DMN3730UFB4**

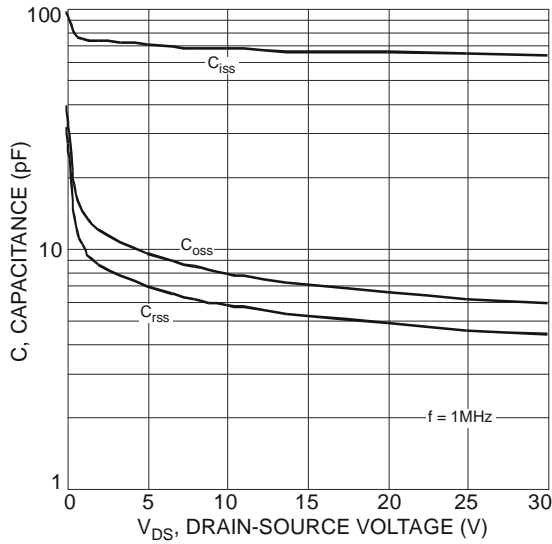


Fig. 9 Typical Total Capacitance

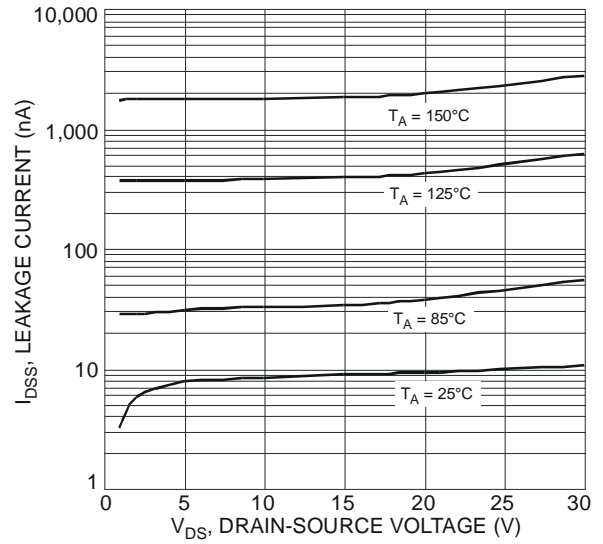


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

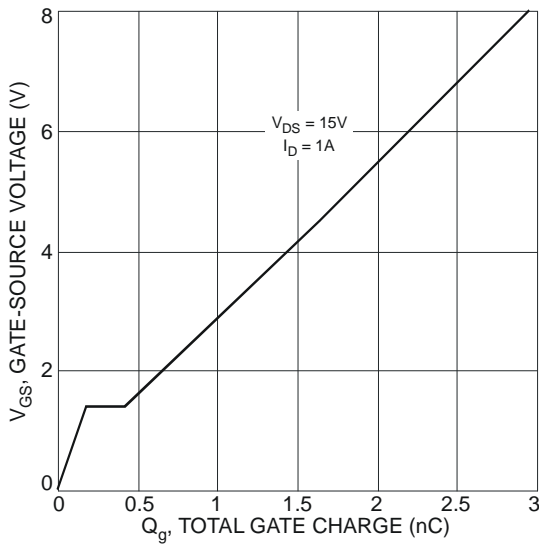


Fig. 11 Gate-Charge Characteristics

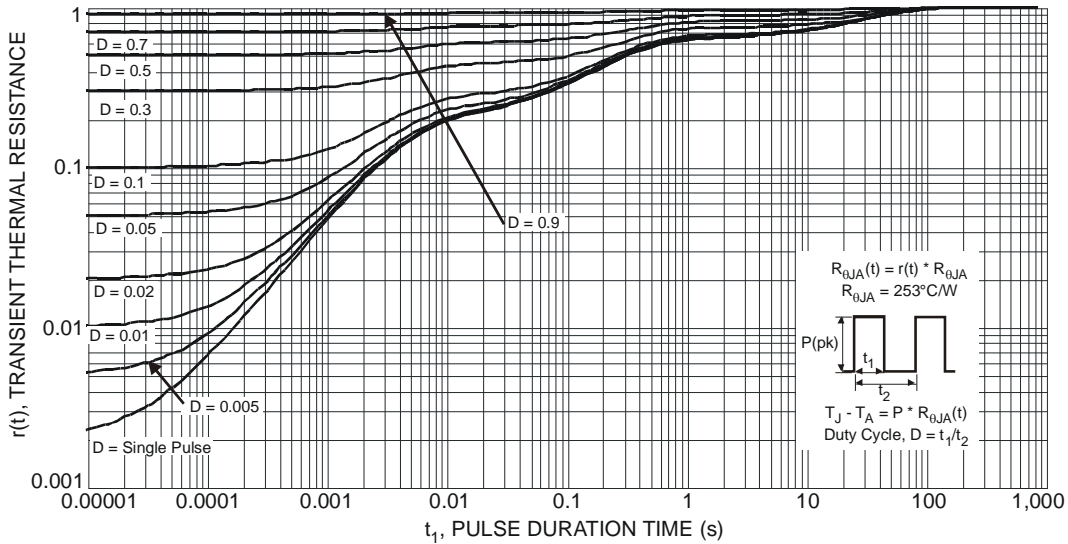
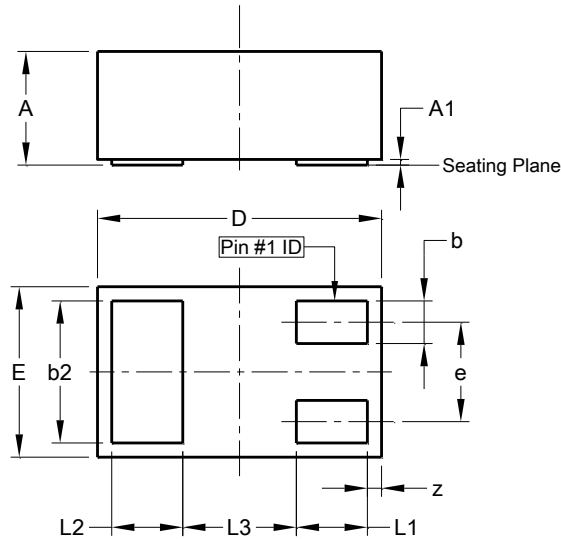


Fig. 12 Transient Thermal Response

## Package Outline Dimensions

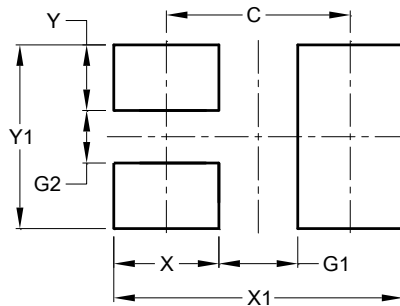
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1006-3			
Dim	Min	Max	Typ
A	—	0.40	—
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.05	1.00
E	0.55	0.65	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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